CONTROL& MONITOR INTERFACE CARD FOR IF ATTENUATION CIRCUITS

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ABSTRACT:

An MCM interface card for IF attenuator and monitor circuits in the Base band system has been developed as a project in STP. This card also facilitates ALC ON/OFF control bits to be separately controlled from the control room. The circuit is designed, its prototype is wired and tested on a general purpose circuit board. Final PCB layout is prepared on PADS software for this circuit using both SMD and DIP package devices.

NEED :

Correlator input (Baseband output) should be at equal power levels (0 dBm) for all antennas for its proper functioning. The IF power levels send to central electronics building from antennas is maintained at -20 dBm/channel using ALC circuits in antenna electronics. In the baseband system there is no facility currently available to vary the input power level. This sometimes leads to different power levels being fed to the Correlator. So it is proposed to use variable attenuator to control IF power from each antenna. The circuit is also planned to facilitate injection of a known noise signal to Baseband input so that Baseband and Correlator can be tested. Details of the proposed system is given in Annexure 1.

As a part of this project a Control and Monitor circuit has been developed to interface the MCM card to the Digital Switchable Attenuators and ALC ON/OFF switches.

AIM:

It is planned to install one MCM card along with one interface card in the baseband rack to take care of eight antenna, one polarization. One MCM card provides 16 TTL control bits and 64 analog monitoring channels. The interface card expands this to 92 digital control bits required for,

4*8=32 for controlling eight Digital Attenuators
2*8=16 for input control of eight antennas using a RF Switch
8*2=16 for selection of signal to be monitored in two PIUs
4 for ADG 506
16 for ALC ON\OFF control
8 for combined monitoring through four way switch i.e PIU 3

The circuit facilitates additional analog monitor channels to monitor the controlled bits as well as the voltages and currents inside the units.

CIRCUIT DESCRIPTION :

8255 IC has three 8 bit ports that can be addressed individually. Three 8255s are required in this card. These three 8255 ICs are configured in mode 0 i.e. no handshaking involved and all ports are defined as output ports. 16 TTL outputs from MCM card are fed to this interface card and are distributed as shown in the diagram.

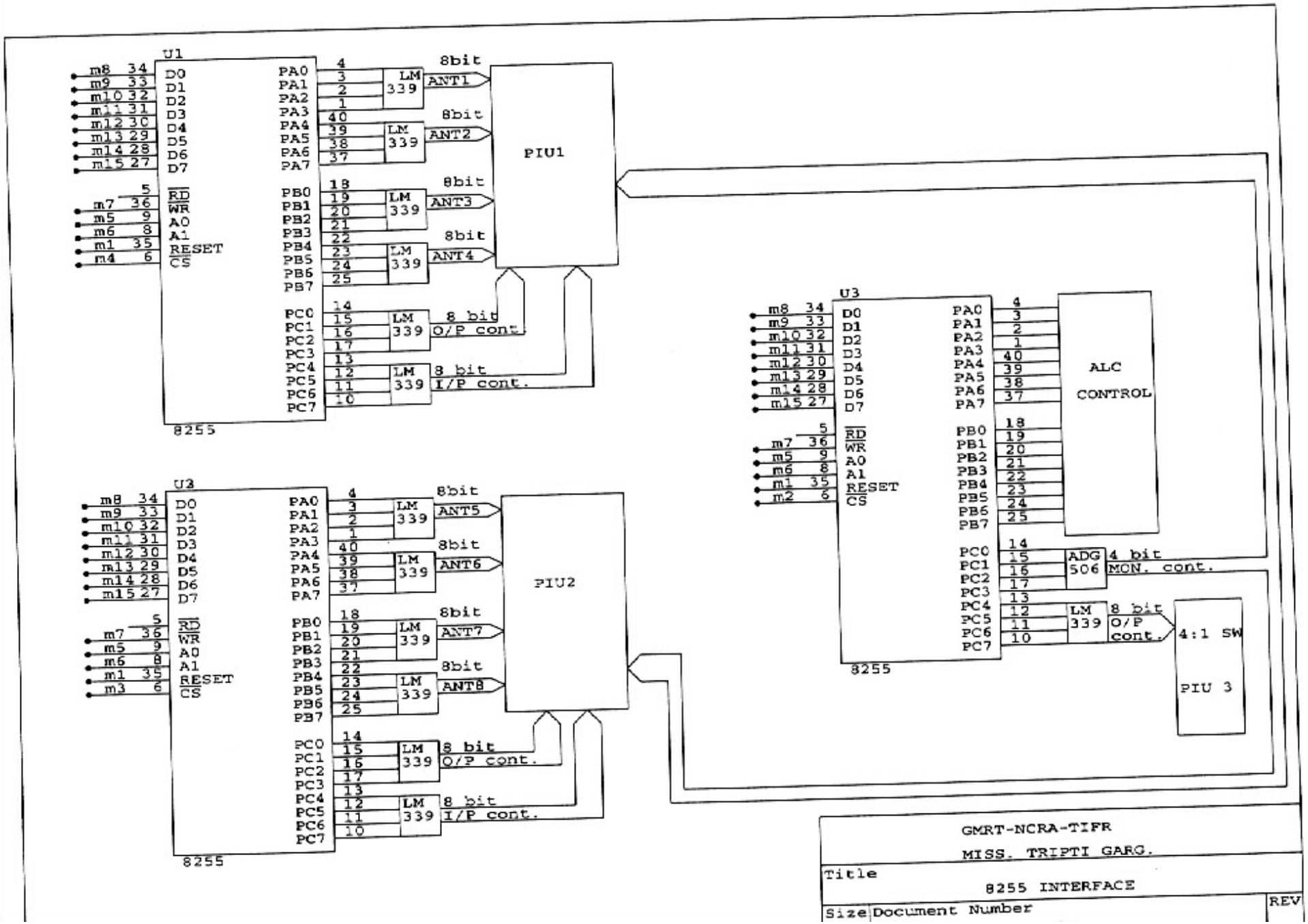
Distribution of MCM lines -

1. The higher order bits of the MCM are used as 8 data lines of 8255 ICs, i.e. m8-m15 as D0 to D7 input to the interface card.
2. MCM output bit m7 is used as active low write signal for 8255.
3. The active low read signal is connected to +VCC as all the ports are used in write mode 0 only.
4. Bits m5 and m6 are connected to A0 and A1 of 8255 for addressing ports or control register.
5. Bits m2, m3 and m4 are connected to the active low chip select signal of 8255.
6. Bit m1 is connected to reset pin. Instead of connecting it directly we used diodes 1N4007 which act as OR gate. This Allows 8255 reset by either power supply or bit m1.
7. Bit m0 is no connection. It is a free bit which can be used for further expansion of this card.

8255A: (PIU1)

Control inputs required for variable attenuators are at level 0 and negative hence the TTL output from 8255 IC has to be level converted before applying them to attenuators. Hence 8 bits from Port A and Port B are connected as input to LM 339. All LM 339 ICs have each bit connected to Inv. And Ninv. Inputs for comparing it with VR i.e reference voltage hence we get 32 level converted control signals for 4 attenuators in PIU1.
Port C upper uses similar logic to generate 8 control lines for input control of four antennas. Port C lower generates 8 control lines for monitoring.

BLOCK DIAGRAM



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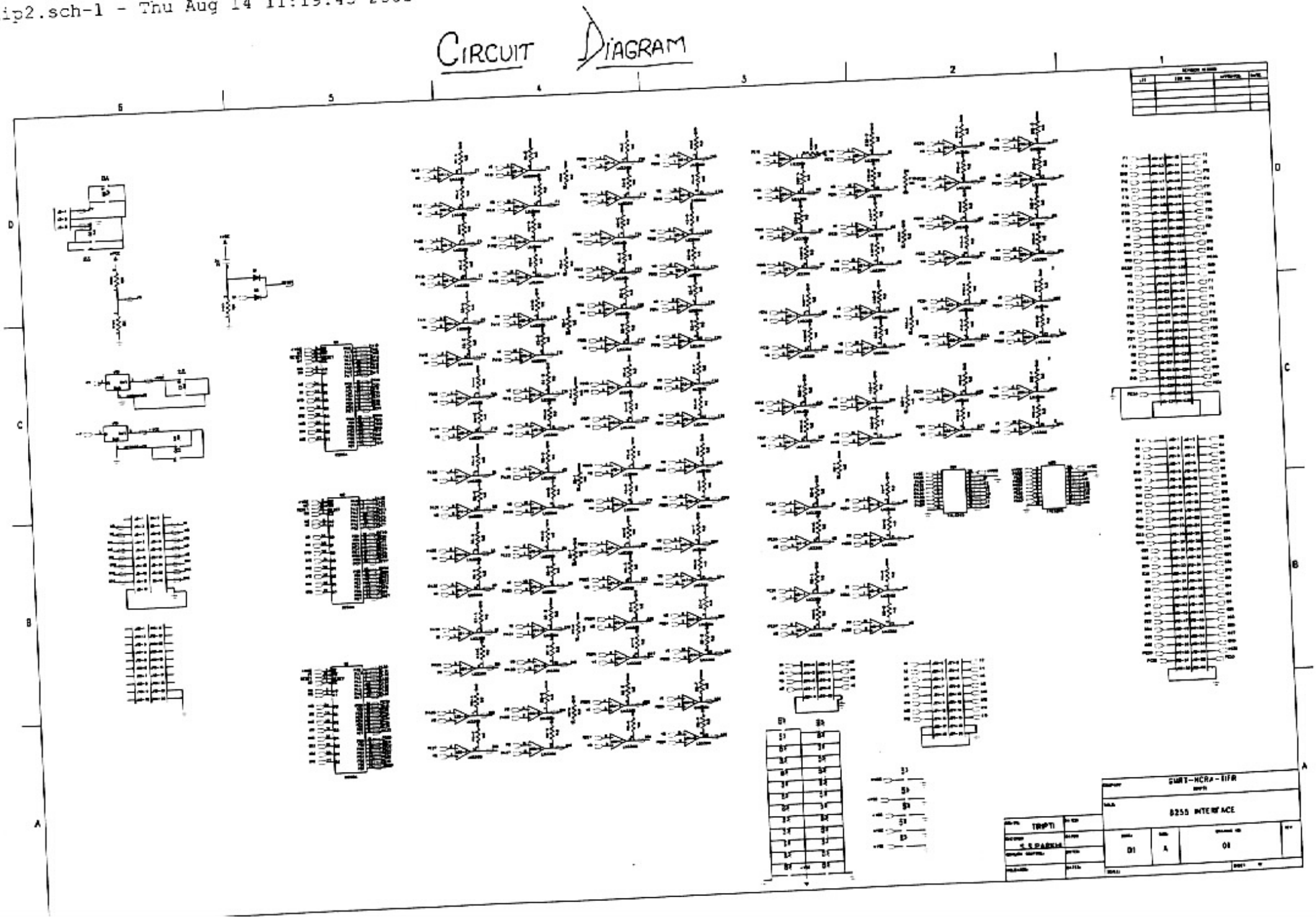
CIRCUIT DIAGRAM



8255 B: (PIU2)
Is connected to PIU2 for attenuation control ,input control and monitoring. Circuit is same as 8255 A.

8255C : (PIU3,ALC,ADG506)
Port A and Port B are connected to 74245 transreciever-driver IC. These bits are used for ALC control. 4 bits of Port C upper are used for ADG 506 control lines. 4 bits of Port C lower are used for combined monitoring for PIU3 with level conversion.

Description of connectors used:

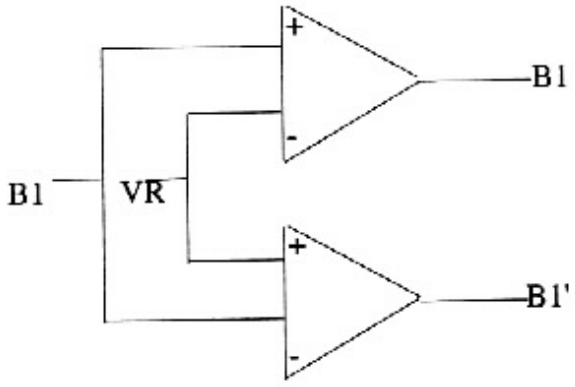
1. A 3 pin relimate connector is used for power supply.
2. Two 20 pin FRC connectors are used for MCM control output.
   Second connector is reserved for future expansion.
3. A 20 pin FRC connector is used for the ALC bits.
4. A10 pin FRC connector is used for PIU3.
5. A 64 pin FRC connector is used for terminating the control bits for PIU2.
6. A 64 pin Euro right angled connector is used for PIU1.

POWER SUPPLY BLOCK :

This card uses two voltage regulator ICs i.e. 7805 for 5 V positive voltage and 7906 for 5 V negative voltage regulation . The supply currents are:
-150 mA at -ve voltage
+100 mA at +ve voltage

LM 339 BLOCK :

LM 339 is a quad comparator IC. It is used as a level convertor, as Digital Variable Attenuators are not TTL compatible. Hence we use LM 339 IC for level conversion .



VR - Refrence voltage
B1 - Data
B1'- conjugate of data

IC 8255 BLOCK :

IC 8255 is a programmable peripheral IC. A control word is written in control register of a selected chip to assign output mode to all its ports. A strobed write signal is fed for writing data to the Ports. Then data is fed to the required ports according to the selected attenuator and attenuation.
Suppose the third attenuator is selected for 4 dB attenuation .Series of hex code required for this purpose is as follows:

Control word	80EC
	806C
	80EC
Port selection	ExAC
	Ex2C
	ExAC

WIRING AND TESTING:

Wired card is tested using MCM and its available software MCMPRNN for communication. The circuit is found to work as per requirement. Steps followed for testing :-

1. Comport address is provided.
2. MCM address 0 is selected for testing.
3. NULL command is issued to check the communication.
4. Command 04 is issued for set digital mask.
5. Control word is written in the control register of selected IC.
6. Particular data is written in specific port for attenuation.
7. Communication is checked at connectors.
8. All possible data configurations are fed and checked.

PCB DESIGN :

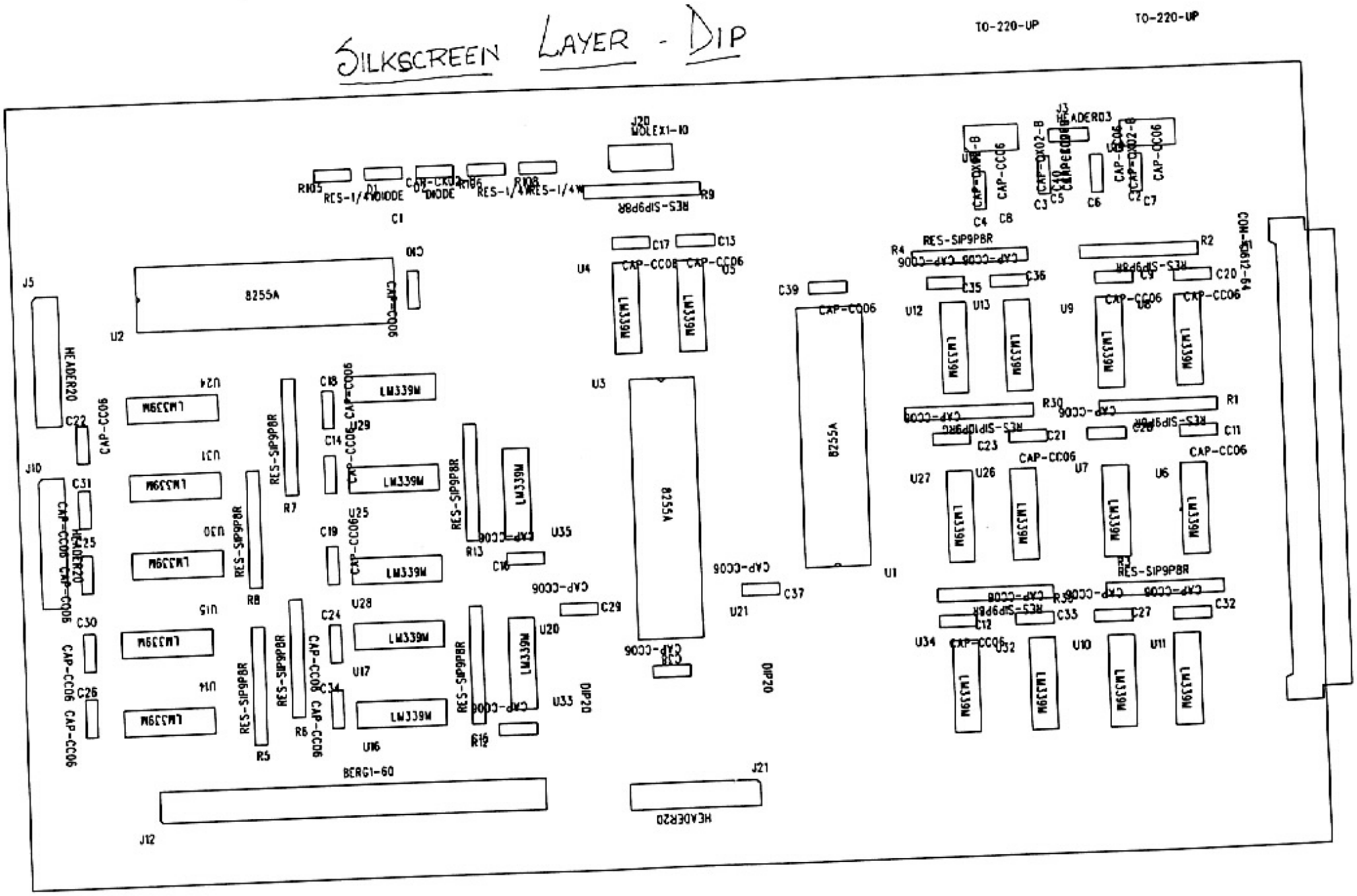
Final PCB layout is designed on PADS software for both SMD and DIP package devices using autorouting. PCB can be viewed in the enclosed diagram.
Specifications for PCB for DIP package devices:

- Components are placed on the top layer only.
- Board size : 10x6 inches
- Pads size Inner dia. : 35 mils, Outer dia. =50 mils
- Track width : 20 mils(VCC,GND), 10 mils for others
- Clearance : 10 mils

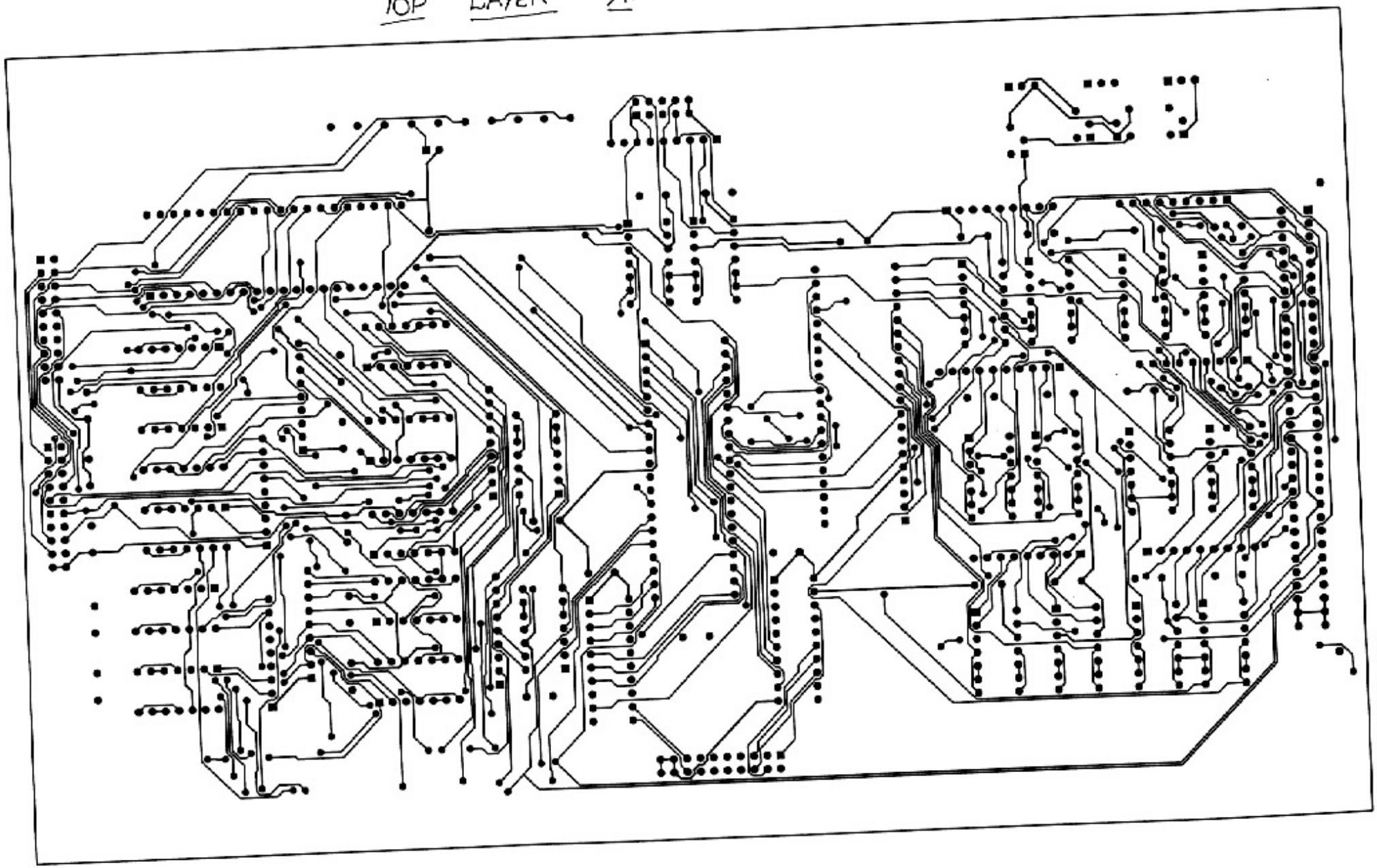
For SMD package devices

- Components are placed on both the layers
- Board size : 8.3x5.5 inches
- Pads size Inner dia. : 35 mils, Outer dia. =50 mils
- Track width : 20 mils(VCC,GND), 10 mils for others
- Clearance :10 mils

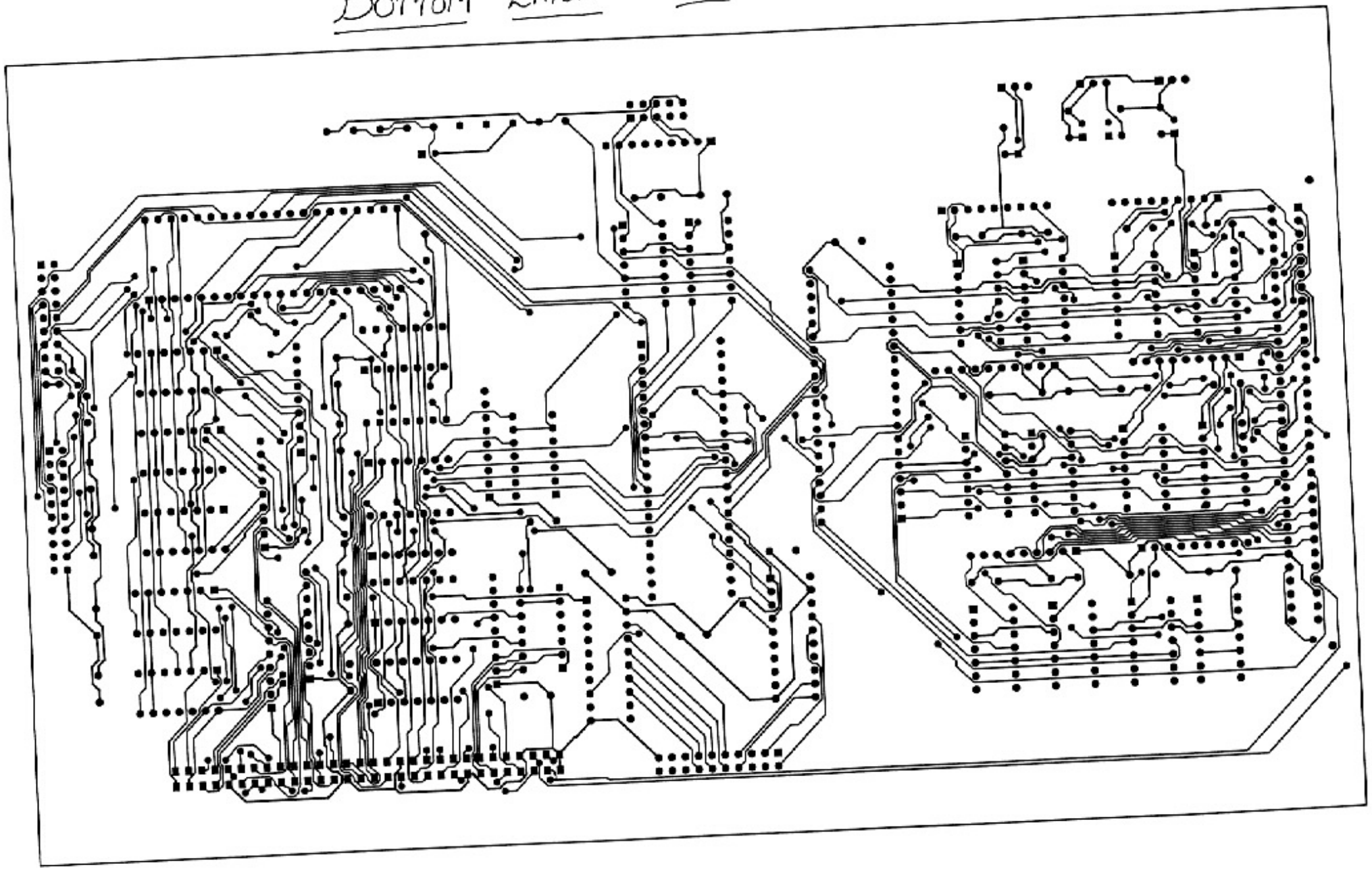
SILKSCREEN LAYER - DIP



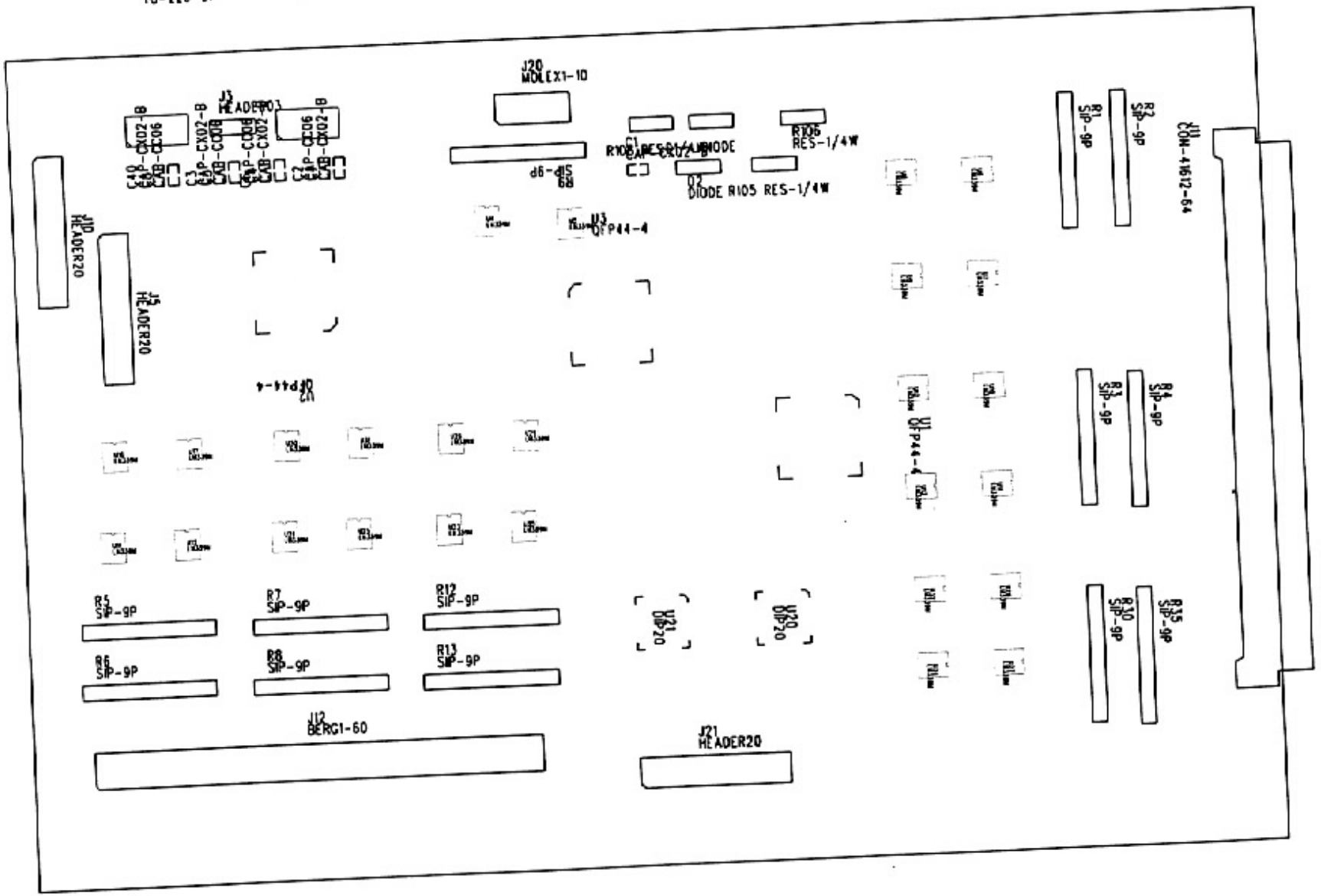
Top Layer - Dip



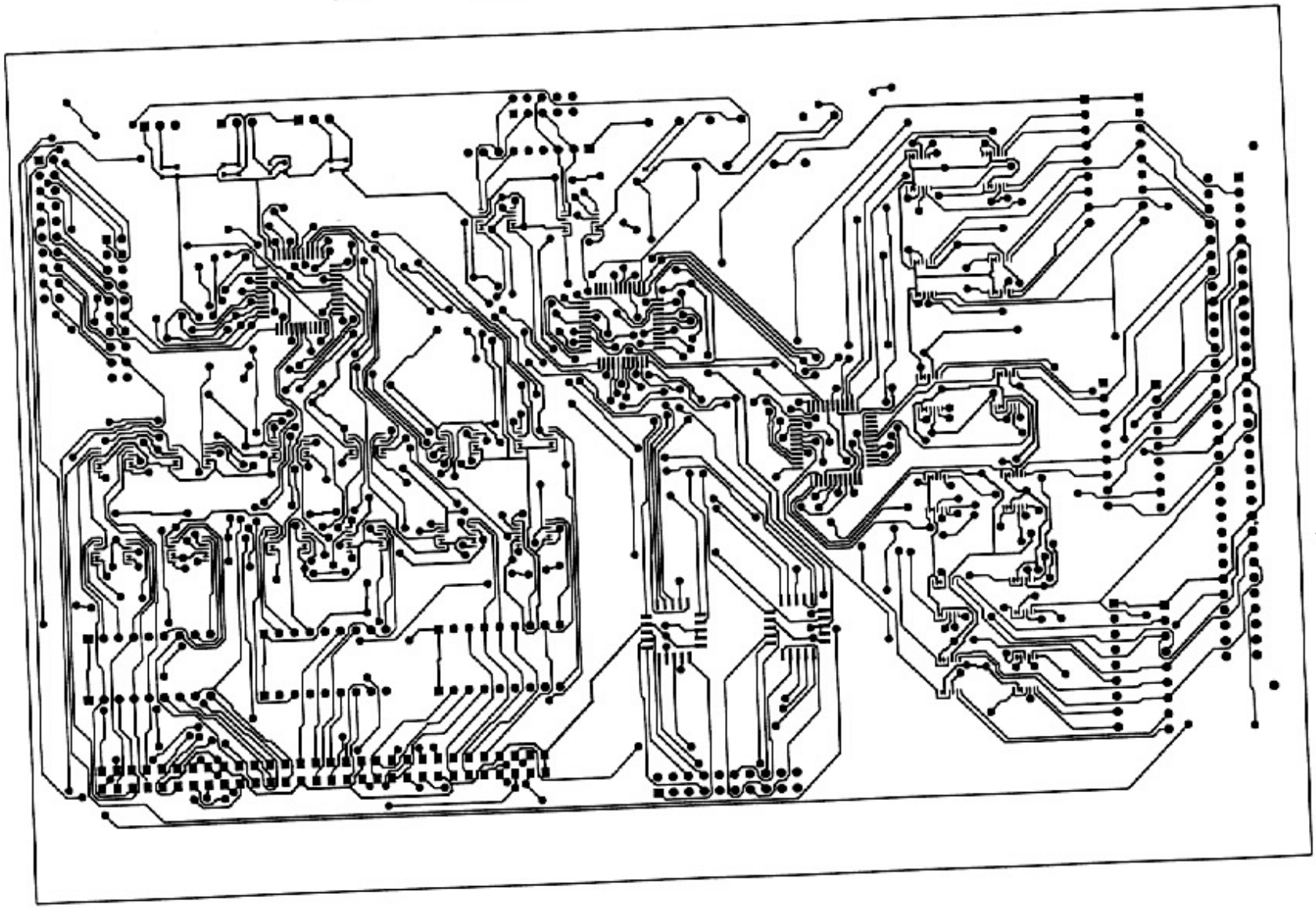
Bottom Layer - Dip



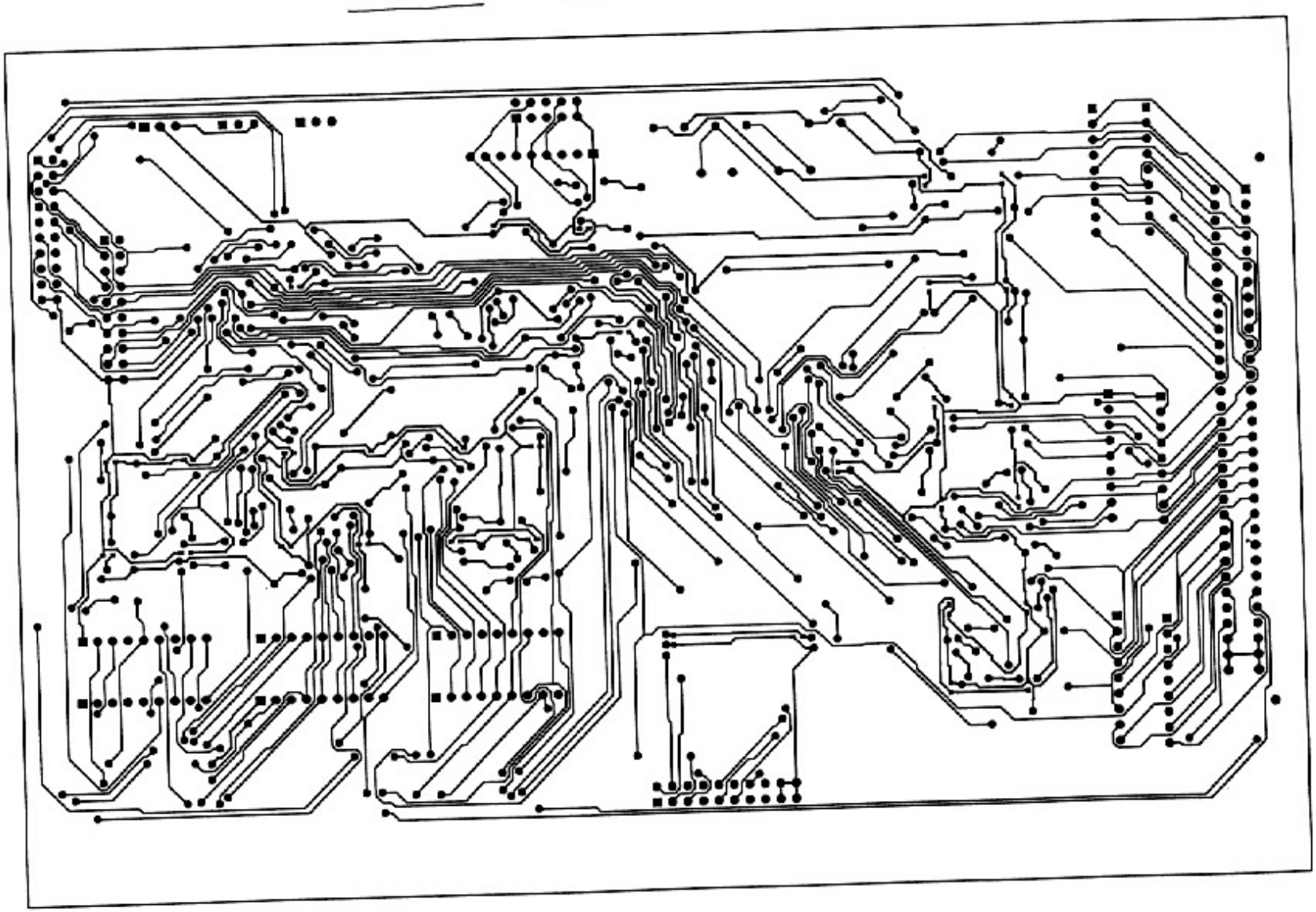
SILKSCREEN - SMD



Top Layer - SMD



Bottom Layer - SMD



CONCLUSION:

Interface card is wired and tested for all data combinations. PCB layout for this card is also prepared on PADS software for both DIP and SMD package devices. A software is written in C to generate the control word according to the selection i.e. Attenuator,ALC etc.

FUTURE SCOPE:

- The package,SMD or DIP, of the of the devices is to be finalised. Then the PCB has to be prepared and wired.
- A software has to be developed for this card to control its parameters from PC.
- To reduce the size and design complexity of PCB, RF attenuators with integral driver i.e. TTL compatible can be used.
- There is a provision for further expansion of this card, as bit m0 from MCM is not connected and an extra 20 pin FRC MCM connector is placed on this card, to expand the MCM digital control bits if needed in future.

REFRENCES:

- Programmable peripheral devices.
- www.intel.com
- www.Motorola.com
- Datasheets of 8255 IC,LM339 IC,74245 IC,7906 IC&7805 IC

AKNOWLEDGEMENT:

I sincerely thank *Prof. S. Ananthakrishnan*, observatory director, GMRT and *Mr. A.B.Joshi*, for giving me an opportunity to work at GMRT project site.

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ANNEXURE I

PIU LEVEL DIAGRAM EXPLANATION:

J51 PIU (PIU0)

This is MCM PIU. It will have MCM card and the bus expansion card along with level conversion for RF attenuators.

MCM CARD -

MCM is general purpose micro controller based card which provide 16 TTL outputs and can monitor 64 analog input signals. MCM cards are interface to all GMRT subsystems like the front end ,the LO etc

BUS EXPANSION AND LEVEL CONVERTOR CARD -

16 control lines from MCM card are not sufficient hence a bus expansion card is designed to increase 16 bits to 72 control bits using peripheral programmable IC 8255, these bits are further expanded and level converted using IC LM339.

This card will have supply voltage regulator IC's 7805 and 7906, it also provides control bits for ADG 506 to monitor controls in actual i.e after level conversion.

J52 PIU (PIU1)

This unit will have four variable attenuators, one power supply card and card with ADG 506 for monitoring. It will have a two way switch to choose a input IF or noise. Noise is fed to all the antennas through a four way power splitter. It will also have a four way switch for monitoring i.e. to choose one output from the four antennas.
The 52 control inputs from the MCM is divided to each of the units as :

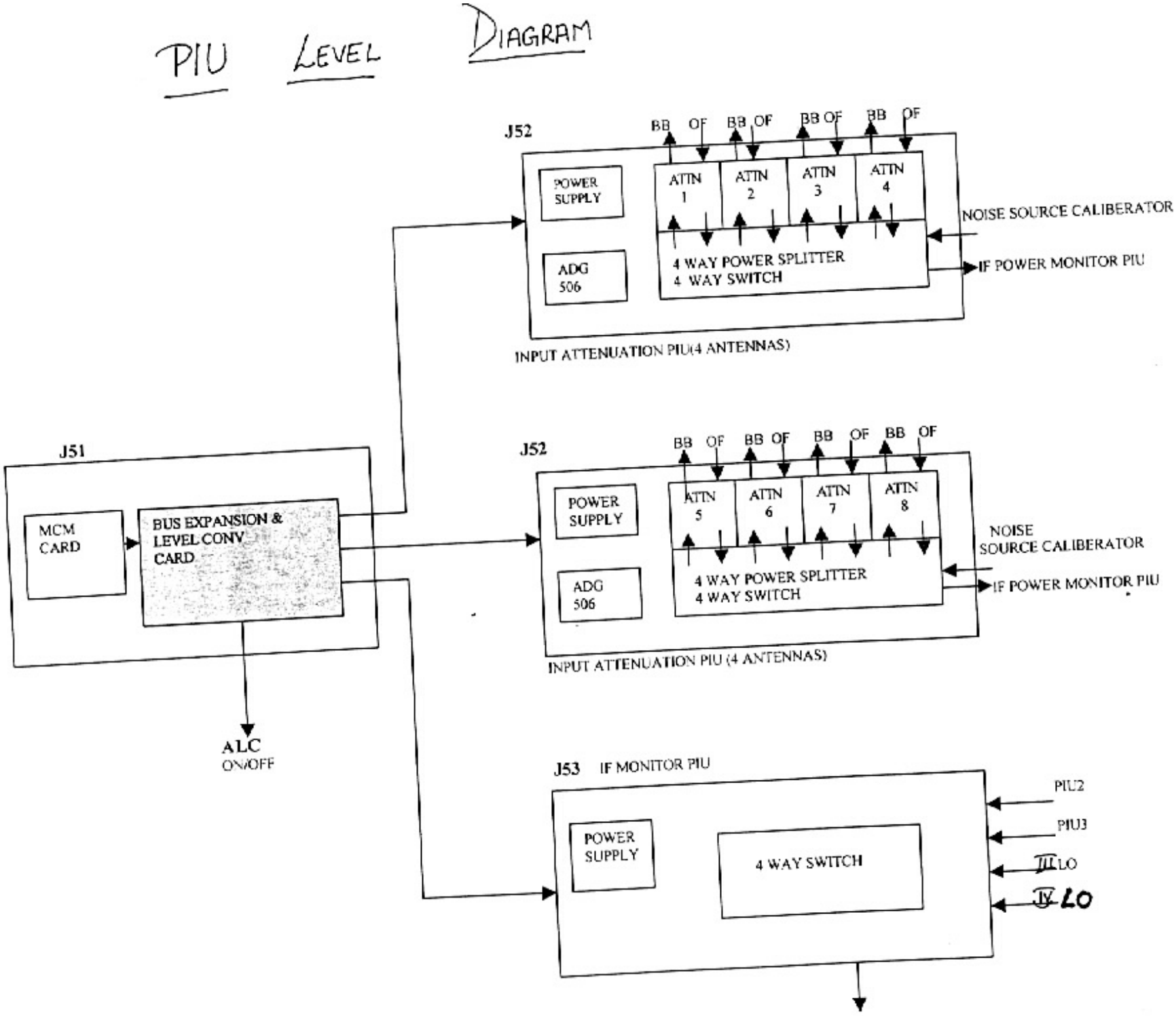
8 * 4=32 for 4 variable attenuators
2 * 4=8 for input control of the 4 antennas
8 for selecting o/p from 4 antennas
4 for ADG 506 control lines

J52 PIU(PIU 2) It is same as PIU1.

J53 PIU(PIU3)

This unit will have a power supply and a four way switch. The output of PIU2 and PIU3 are fed to this PIU along with two Los. The four way switch sitting in the PIU is for combined monitoring i.e to select one of the four inputs fed to it. It receives four control lines from MCM for this purpose.

PIU LEVEL DIAGRAM



ANNEXURE - 2.

82C55A
CHMOS PROGRAMMABLE PERIPHERAL INTERFACE

- Compatible with all Intel and Most Other Microprocessors
- High Speed, "Zero Wait State" Operation with 8 MHz 8086/88 and 80186/188
- 24 Programmable I/O Pins
- Low Power CHMOS
- Completely TTL Compatible
- Control Word Read-Back Capability
- Direct Bit Set/Reset Capability
- 2.5 mA DC Drive Capability on all I/O Port Outputs
- Available in 40-Pin DIP and 44-Pin PLCC
- Available in EXPRESS
  - Standard Temperature Range
  - Extended Temperature Range

The Intel 82C55A is a high-performance, CHMOS version of the industry standard 8255A general purpose programmable I/O device which is designed for use with all Intel and most other microprocessors. It provides 24 I/O pins which may be individually programmed in 2 groups of 12 and used in 3 major modes of operation. The 82C55A is pin compatible with the NMOS 8255A and 8255A-5.

In MODE 0, each group of 12 I/O pins may be programmed in sets of 4 and 8 to be inputs or outputs. In MODE 1, each group may be programmed to have 8 lines of input or output. 3 of the remaining 4 pins are used for handshaking and interrupt control signals. MODE 2 is a strobed bi-directional bus configuration.

The 82C55A is fabricated on Intel's advanced CHMOS III technology which provides low power consumption with performance equal to or greater than the equivalent NMOS product. The 82C55A is available in 40-pin DIP and 44-pin plastic leaded chip carrier (PLCC) packages.

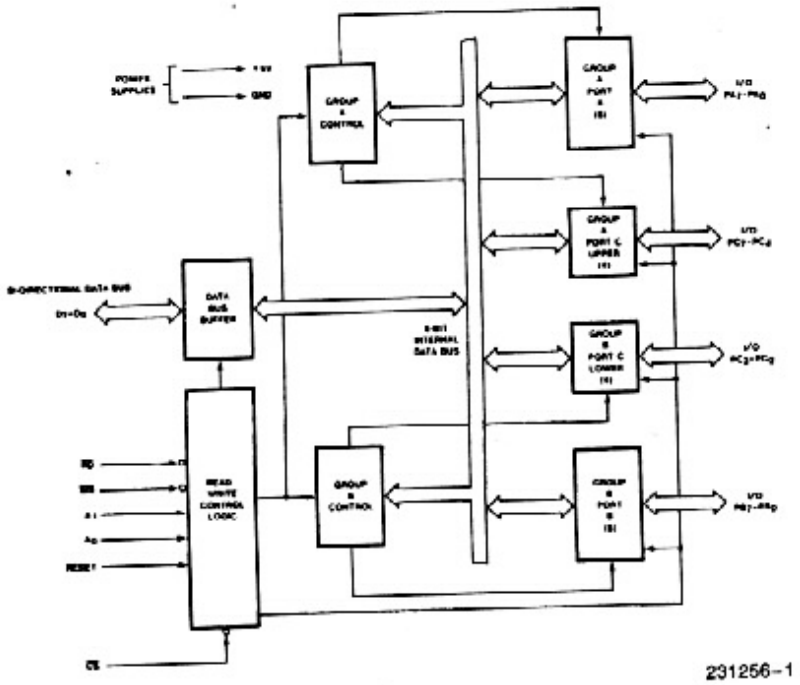


Figure 1. 82C55A Block Diagram

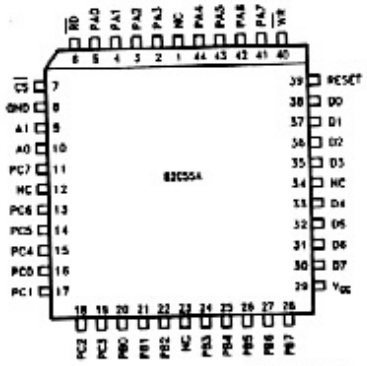


Figure 2. 82C55A Pinout
Diagrams are for pin reference only. Package sizes are not to scale.

October 1995

Order Number: 231256-004

Table 1. Pin Description

Symbol	Pin Number Dip	Pin Number PLCC	Type	Name and Function
PA_{3-0}	1–4	2–5	I/O	**PORT A, PINS 0–3:** Lower nibble of an 8-bit data output latch/ buffer and an 8-bit data input latch.
$\overline{RD}$	5	6	I	**READ CONTROL:** This input is low during CPU read operations.
$\overline{CS}$	6	7	I	**CHIP SELECT:** A low on this input enables the 82C55A to respond to $\overline{RD}$ and $\overline{WR}$ signals. $\overline{RD}$ and WR are ignored otherwise.
GND	7	8		**System Ground**
A_{1-0}	8–9	9–10	I	**ADDRESS:** These input signals, in conjunction $\overline{RD}$ and $\overline{WR}$, control the selection of one of the three ports or the control word registers.

A_1	A_0	$\overline{RD}$	$\overline{WR}$	$\overline{CS}$	Input Operation (Read)
0	0	0	1	0	Port A - Data Bus
0	1	0	1	0	Port B - Data Bus
1	0	0	1	0	Port C - Data Bus
1	1	0	1	0	Control Word - Data Bus
					Output Operation (Write)
0	0	1	0	0	Data Bus - Port A
0	1	1	0	0	Data Bus - Port B
1	0	1	0	0	Data Bus - Port C
1	1	1	0	0	Data Bus - Control
					Disable Function
X	X	X	X	1	Data Bus - 3 - State
X	X	1	1	0	Data Bus - 3 - State

PC_{7-4}	10–13	11,13–15	I/O	**PORT C, PINS 4–7:** Upper nibble of an 8-bit data output latch/ buffer and an 8-bit data input buffer (no latch for input). This port can be divided into two 4-bit ports under the mode control. Each 4-bit port contains a 4-bit latch and it can be used for the control signal outputs and status signal inputs in conjunction with ports A and B.
PC_{0-3}	14–17	16–19	I/O	**PORT C, PINS 0–3:** Lower nibble of Port C.
PB_{0-7}	18–25	20–22, 24–28	I/O	**PORT B, PINS 0–7:** An 8-bit data output latch/buffer and an 8-bit data input buffer.
V_{CC}	26	29		**SYSTEM POWER:** + 5V Power Supply.
D_{7-0}	27–34	30–33, 35–38	I/O	**DATA BUS:** Bi-directional, tri-state data bus lines, connected to system data bus.
RESET	35	39	I	**RESET:** A high on this input clears the control register and all ports are set to the input mode.
$\overline{WR}$	36	40	I	**WRITE CONTROL:** This input is low during CPU write operations.
PA_{7-4}	37–40	41–44	I/O	**PORT A, PINS 4–7:** Upper nibble of an 8-bit data output latch/ buffer and an 8-bit data input latch.
NC		1, 12, 23, 34		No Connect

82C55A FUNCTIONAL DESCRIPTION

General

The 82C55A is a programmable peripheral interface device designed for use in Intel microcomputer systems. Its function is that of a general purpose I/O component to interface peripheral equipment to the microcomputer system bus. The functional configuration of the 82C55A is programmed by the system software so that normally no external logic is necessary to interface peripheral devices or structures.

Data Bus Buffer

This 3-state bidirectional 8-bit buffer is used to interface the 82C55A to the system data bus. Data is transmitted or received by the buffer upon execution of input or output instructions by the CPU. Control words and status information are also transferred through the data bus buffer.

Read/Write and Control Logic

The function of this block is to manage all of the internal and external transfers of both Data and Control or Status words. It accepts inputs from the CPU Address and Control busses and in turn, issues commands to both of the Control Groups.

Group A and Group B Controls

The functional configuration of each port is programmed by the systems software. In essence, the CPU "outputs" a control word to the 82C55A. The control word contains information such as "mode", "bit set", "bit reset", etc., that initializes the functional configuration of the 82C55A.

Each of the Control blocks (Group A and Group B) accepts "commands" from the Read/Write Control Logic, receives "control words" from the internal data bus and issues the proper commands to its associated ports.

Control Group A - Port A and Port C upper (C7–C4)
Control Group B - Port B and Port C lower (C3–C0)

The control word register can be both written and read as shown in the address decode table in the pin descriptions. Figure 6 shows the control word format for both Read and Write operations. When the control word is read, bit D7 will always be a logic "1", as this implies control word mode information.

Ports A, B, and C

The 82C55A contains three 8-bit ports (A, B, and C). All can be configured in a wide variety of functional characteristics by the system software but each has its own special features or "personality" to further enhance the power and flexibility of the 82C55A.

Port A. One 8-bit data output latch/buffer and one 8-bit input latch buffer. Both "pull-up" and "pull-down" bus hold devices are present on Port A.

Port B. One 8-bit data input/output latch/buffer. Only "pull-up" bus hold devices are present on Port B.

Port C. One 8-bit data output latch/buffer and one 8-bit data input buffer (no latch for input). This port can be divided into two 4-bit ports under the mode control. Each 4-bit port contains a 4-bit latch and it can be used for the control signal outputs and status signal inputs in conjunction with ports A and B. Only "pull-up" bus hold devices are present on Port C.

See Figure 4 for the bus-hold circuit configuration for Port A, B, and C.

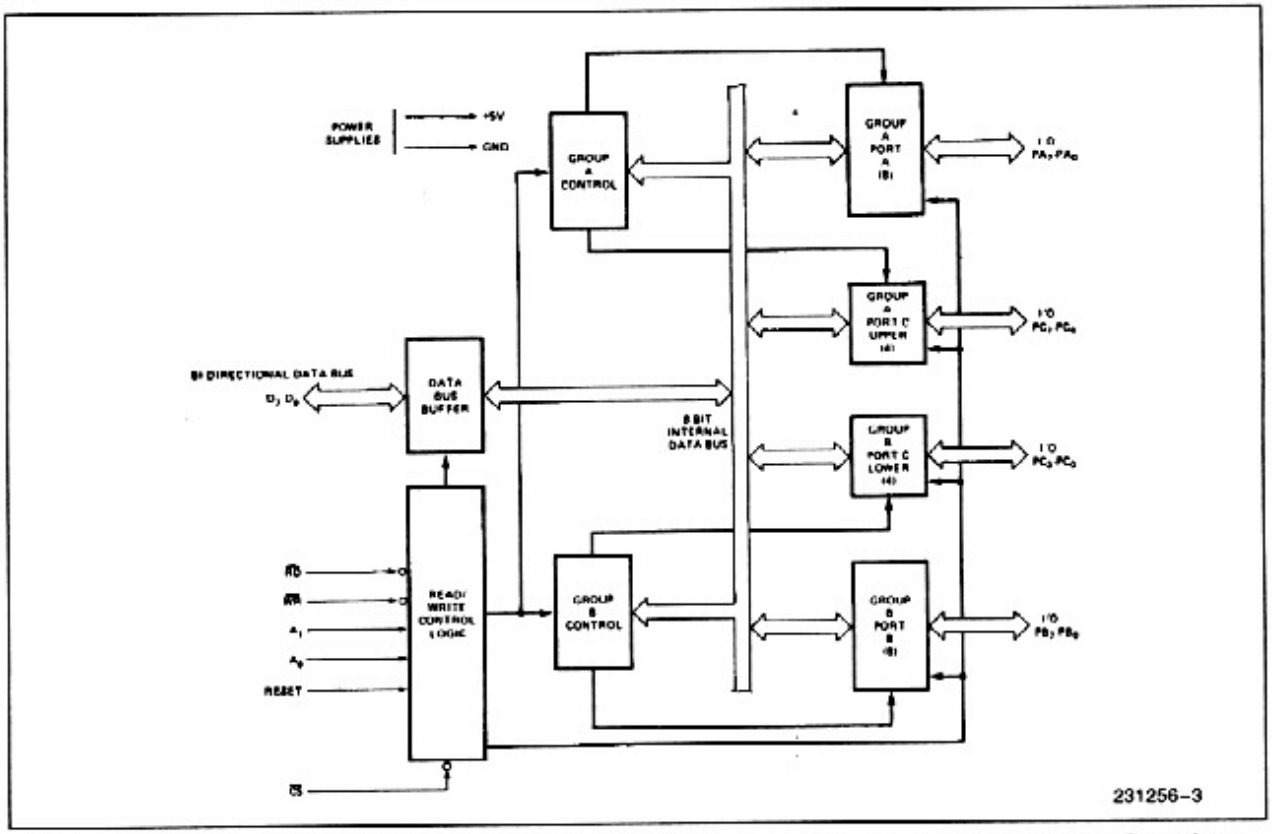
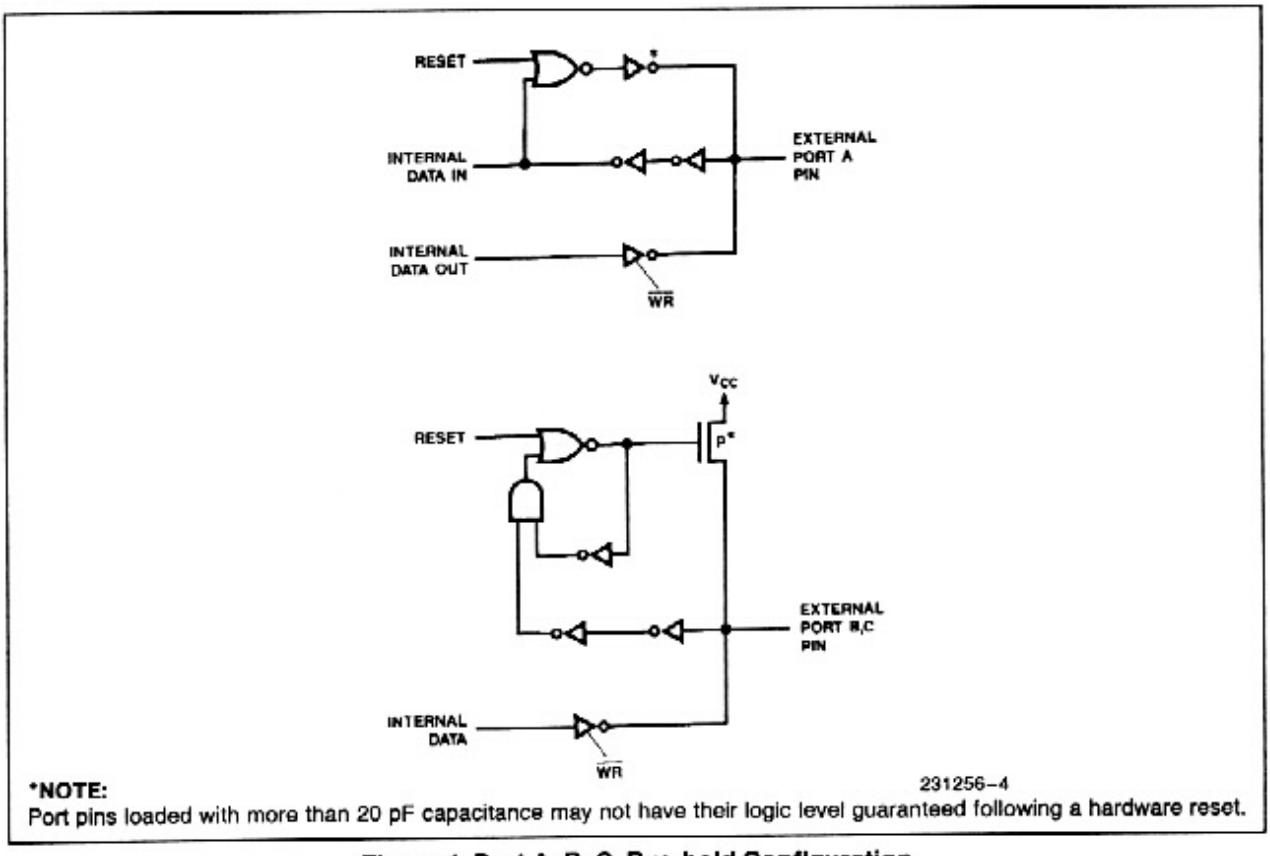


Figure 3. 82C55A Block Diagram Showing Data Bus Buffer and Read/Write Control Logic Functions



***NOTE:**
Port pins loaded with more than 20 pF capacitance may not have their logic level guaranteed following a hardware reset.

Figure 4. Port A, B, C, Bus-hold Configuration

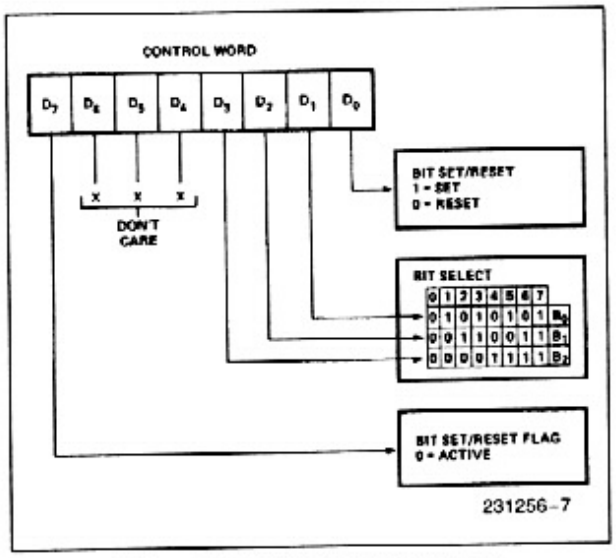


Figure 7. Bit Set/Reset Format

Interrupt Control Functions

When the 82C55A is programmed to operate in mode 1 or mode 2, control signals are provided that can be used as interrupt request inputs to the CPU. The interrupt request signals, generated from port C, can be inhibited or enabled by setting or resetting the associated INTE flip-flop, using the bit set/reset function of port C.

This function allows the Programmer to disallow or allow a specific I/O device to interrupt the CPU without affecting any other device in the interrupt structure.

INTE flip-flop definition:

(BIT-SET)—INTE is SET—Interrupt enable
(BIT-RESET)—INTE is RESET—Interrupt disable

Note:
All Mask flip-flops are automatically reset during mode selection and device Reset.

ANNEXURE - 3

Order this document by LM339/D

MOTOROLA

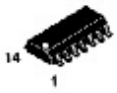
LM339, LM339A, LM239, LM239A, LM2901, M2901V, MC3302

Quad Single Supply Comparators

These comparators are designed for use in level detection, low–level sensing and memory applications in consumer automotive and industrial electronic applications.

- Single or Split Supply Operation
- Low Input Bias Current: 25 nA (Typ)
- Low Input Offset Current: ±5.0 nA (Typ)
- Low Input Offset Voltage: ±1.0 mV (Typ) LM139A Series
- Input Common Mode Voltage Range to Gnd
- Low Output Saturation Voltage: 130 mV (Typ) @ 4.0 mA
- TTL and CMOS Compatible
- ESD Clamps on the Inputs Increase Reliability without Affecting Device Operation

N, P SUFFIX
PLASTIC PACKAGE
CASE 646



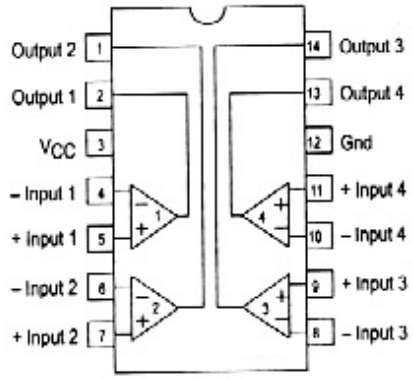
D SUFFIX
PLASTIC PACKAGE
CASE 751A
(SO–14)

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Supply Voltage LM239, A/LM339A/LM2901, V MC3302	V_{CC}	 +36 or ±18 +30 or ±15	Vdc
Input Differential Voltage Range LM239, A/LM339A/LM2901, V MC3302	V_{IDR}	 36 30	Vdc
Input Common Mode Voltage Range	V_{ICMR}	–0.3 to V_{CC}	Vdc
Output Short Circuit to Ground (Note 1)	I_{SC}	Continuous	
Power Dissipation @ T_A = 25°C Plastic Package Derate above 25°C	P_D	 1.0 8.0	 W mW/°C
Junction Temperature	T_J	150	°C
Operating Ambient Temperature Range LM239, A MC3302 LM2901 LM2901V LM339, A	T_A	 –25 to +85 –40 to +85 –40 to +105 –40 to +125 0 to +70	°C
Storage Temperature Range	T_{stg}	–65 to +150	°C

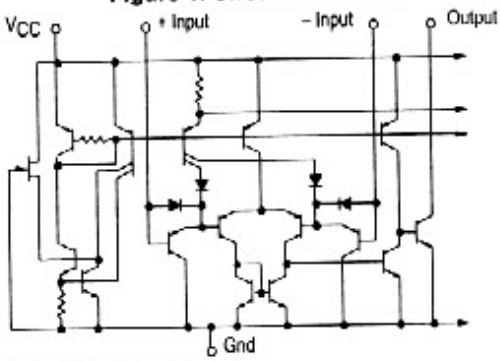
NOTE: 1. The maximum output current may be as high as 20 mA, independent of the magnitude of V_{CC}. Output short circuits to V_{CC} can cause excessive heating and eventual destruction.

PIN CONNECTIONS



(Top View)

Figure 1. Circuit Schematic



NOTE: Diagram shown is for 1 comparator.

ORDERING INFORMATION

Device	Operating Temperature Range	Package
LM239D,AD LM239N,AN	T_A = 25° to +85°C	SO–14 Plastic DIP
LM339D, AD LM339N, AN	T_A = 0° to +70°C	SO–14 Plastic DIP
LM2901D LM2901N	T_A = –40° to +105°C	SO–14 Plastic DIP
LM2901VD LM2901VN	T_A = –40° to +125°C	SO–14 Plastic DIP
MC3302P	T_A = –40° to +85°C	Plastic DIP

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Rev 2

ELECTRICAL CHARACTERISTICS (V_{CC} = +5.0 Vdc, T_A = +25°C, unless otherwise noted)

Characteristic	Symbol	LM239A/339A			LM239/339			LM2901/2901V			MC3302			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage (Note 4)	V_{IO}	–	±1.0	±2.0	–	±2.0	±5.0	–	±2.0	±7.0	–	±3.0	±20	mVdc
Input Bias Current (Notes 4, 5) (Output in Analog Range)	I_{IB}	–	25	250	–	26	250	–	25	250	–	25	500	nA
Input Offset Current (Note 4)	I_{IO}	–	±5.0	±50	–	±5.0	±50	–	±5.0	±50	–	±3.0	±100	nA
Input Common Mode Voltage Range	V_{ICMR}	0	–	V_{CC} –1.5	0	–	V_{CC} –1.5	0	–	V_{CC} –1.5	0	–	V_{CC} –1.5	V
Supply Current R_L = ∞ (For All Comparators) R_L = ∞, V_{CC} = 30 Vdc	I_{CC}	 – –	 0.8 1.0	 2.0 2.5	 – –	 0.8 1.0	 2.0 2.5	 – –	 0.8 1.0	 2.0 2.5	 – –	 0.8 1.0	 2.0 2.5	mA
Voltage Gain R_L ≥ 15 kΩ, V_{CC} = 15 Vdc	A_{VOL}	50	200	–	50	200	–	25	100	–	25	100	–	V/mV
Large Signal Response Time V_I = TTL Logic Swing, V_{ref} = 1.4 Vdc, V_{RL} = 5.0 Vdc, R_L = 5.1 kΩ	–	–	300	–	–	300	–	–	300	–	–	300	–	ns
Response Time (Note 6) V_{RL} = 5.0 Vdc, R_L = 5.1 kΩ	–	–	1.3	–	–	1.3	–	–	1.3	–	–	1.3	–	µs
Output Sink Current V_I (–) ≥ +1.0 Vdc, V_I(+) = 0, V_O ≤ 1.5 Vdc	I_{Sink}	6.0	16	–	6.0	16	–	6.0	16	–	6.0	16	–	mA
Saturation Voltage V_I(–) ≥ +1.0 Vdc, V_I(+) = 0, I_{sink} ≤ 4.0 mA	V_{sat}	–	130	400	–	130	400	–	130	400	–	130	500	mV
Output Leakage Current V_I(+) ≥ +1.0 Vdc, V_I(–) = 0, V_O = +5.0 Vdc	I_{OL}	–	0.1	–	–	0.1	–	–	0.1	–	–	0.1	–	nA

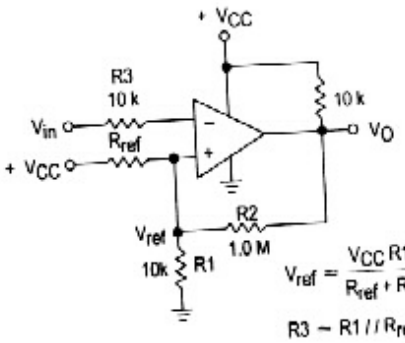
PERFORMANCE CHARACTERISTICS (V_{CC} = +5.0 Vdc, T_A = T_{low} to T_{high} [Note 3])

Characteristic	Symbol	LM239A/339A			LM239/339			LM2901/2901V			MC3302			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage (Note 4)	V_{IO}	–	–	±4.0	–	–	±9.0	–	–	±15	–	–	±40	mVdc
Input Bias Current (Notes 4, 5) (Output in Analog Range)	I_{IB}	–	–	400	–	–	400	–	–	500	–	–	1000	nA
Input Offset Current (Note 4)	I_{IO}	–	–	±150	–	–	±150	–	–	±200	–	–	±300	nA
Input Common Mode Voltage Range	V_{ICMR}	0	–	V_{CC} –2.0	0	–	V_{CC} –2.0	0	–	V_{CC} –2.0	0	–	V_{CC} –2.0	V
Saturation Voltage V_I(–) ≥ +1.0 Vdc, V_I(+) = 0, I_{sink} ≤ 4.0 mA	V_{sat}	–	–	700	–	–	700	–	–	700	–	–	700	mV
Output Leakage Current V_I(+) ≥ +1.0 Vdc, V_I(–) = 0, V_O = 30 Vdc	I_{OL}	–	–	1.0	–	–	1.0	–	–	1.0	–	–	1.0	µA
Differential Input Voltage All V_I ≥ 0 Vdc	V_{ID}	–	–	V_{CC}	–	–	V_{CC}	–	–	V_{CC}	–	–	V_{CC}	Vdc

NOTES: 3. (LM239/239A) T_{low} = –25°C, T_{high} = +85°
(LM339/339A) T_{low} = 0°C, T_{high} = +70°C
(MC3302) T_{low} = –40°C, T_{high} = +85°C
(LM2901) T_{low} = –40°C, T_{high} = +105°
(LM2901V) T_{low} = –40°C, T_{high} = +125°C

4. At the output switch point, V_O = 1.4 Vdc, R_S ≤ 100 Ω 5.0 Vdc ≤ V_{CC} ≤ 30 Vdc, with the inputs over the full common mode range (0 Vdc to V_{CC} –1.5 Vdc).
5. The bias current flows out of the inputs due to the PNP input stage. This current is virtually constant, independent of the output state.
6. The response time specified is for a 100 mV input step with 5.0 mV overdrive. For larger signals, 300 ns is typical.

Figure 2. Inverting Comparator with Hystersis



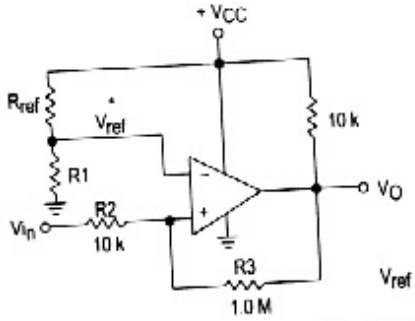
$$V_{ref} = \frac{V_{CC}\,R1}{R_{ref} + R1}$$

$$R3 = R1 \,//\, R_{ref} \,//\, R2$$

$$V_H = \frac{R1 \,//\, R_{ref}}{R1 \,//\, R_{ref} + R2}\,[V_{O(max)} - V_{O(min)}]$$

$$R2 \gg R_{ref} \,//\, R1$$

Figure 3. Noninverting Comparator with Hysteresis



$$V_{ref} = \frac{V_{CC}\,R1}{R_{ref} + R1}$$

$$R2 \approx R1 \,//\, R_{ref}$$

Amount of Hysteresis V_H

$$V_H = \frac{R2}{R2 + R3}\,[V_{O(max)} - V_{O(min)}]$$

Typical Characteristics

(V_{CC} = 15 Vdc, T_A = +25°C (each comparator) unless otherwise noted.)

Figure 4. Normalized Input Offset Voltage

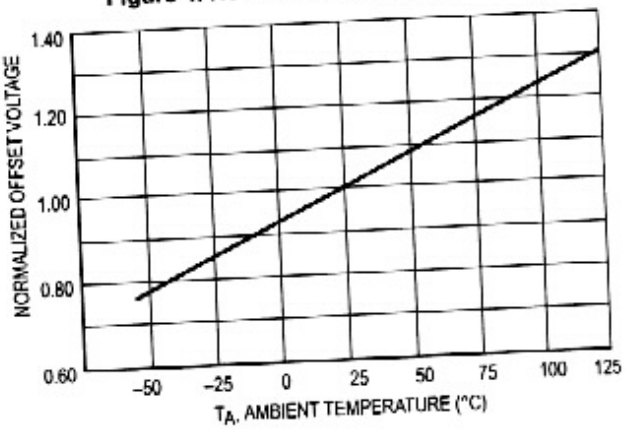


Figure 5. Input Bias Current

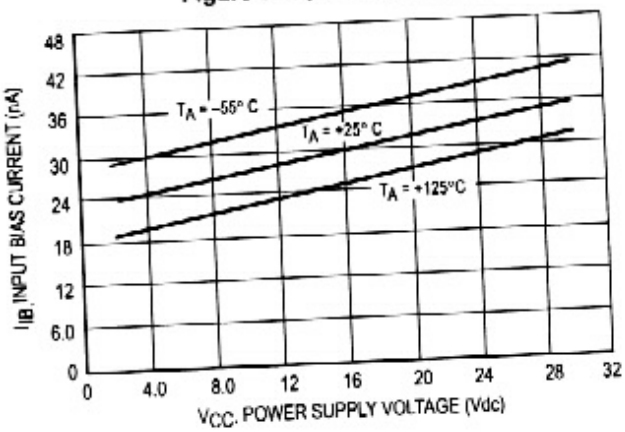
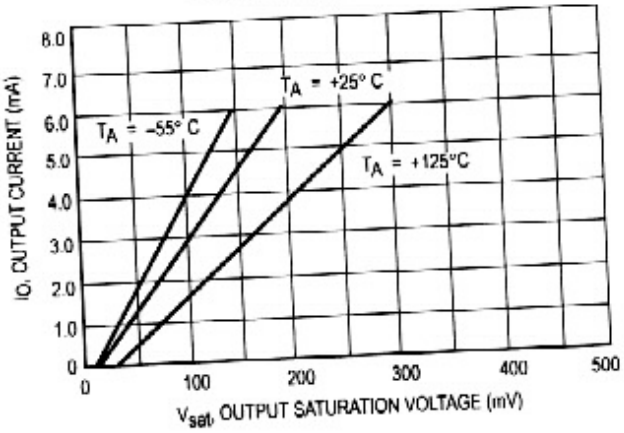


Figure 6. Output Sink Current versus Output Saturation Voltage



ANNEXURE - 4

National Semiconductor

February 1995

LM78XX Series Voltage Regulators

General Description

The LM78XX series of three terminal regulators is available with several fixed output voltages making them useful in a wide range of applications. One of these is local on card regulation, eliminating the distribution problems associated with single point regulation. The voltages available allow these regulators to be used in logic systems, instrumentation, HiFi, and other solid state electronic equipment. Although designed primarily as fixed voltage regulators these devices can be used with external components to obtain adjustable voltages and currents.

The LM78XX series is available in an aluminum TO-3 package which will allow over 1.0A load current if adequate heat sinking is provided. Current limiting is included to limit the peak output current to a safe value. Safe area protection for the output transistor is provided to limit internal power dissipation. If internal power dissipation becomes too high for the heat sinking provided, the thermal shutdown circuit takes over preventing the IC from overheating.

Considerable effort was expanded to make the LM78XX series of regulators easy to use and mininize the number of external components. It is not necessary to bypass the output, although this does improve transient response. Input bypassing is needed only if the regulator is located far from the filter capacitor of the power supply.

For output voltage other than 5V, 12V and 15V the LM117 series provides an output voltage range from 1.2V to 57V.

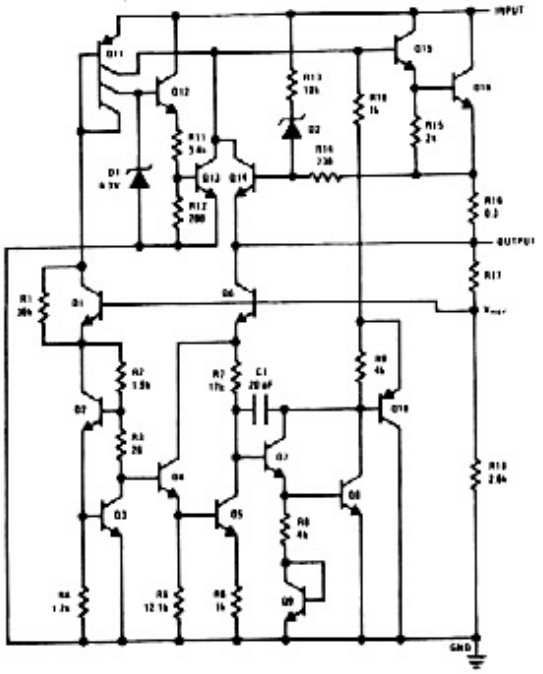
Features

- Output current in excess of 1A
- Internal thermal overload protection
- No external components required
- Output transistor safe area protection
- Internal short circuit current limit
- Available in the aluminum TO-3 package

Voltage Range

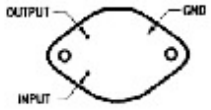
LM7805C	5V
LM7812C	12V
LM7815C	15V

Schematic and Connection Diagrams



TL/H/7746–1

Metal Can Package
TO-3 (K)
Aluminum

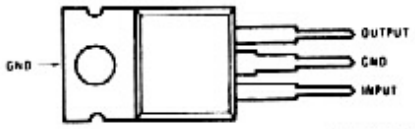


TL/H/7746–2

Bottom View

Order Number LM7805CK, LM7812CK or LM7815CK
See NS Package Number KC02A

Plastic Package
TO-220 (T)



TL/H/7746–3

Top View

Order Number LM7805CT, LM7812CT or LM7815CT
See NS Package Number T03B

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RRD-B30M115/Printed in U. S. A.

Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Input Voltage (V_O = 5V, 12V and 15V)	35V
Internal Power Dissipation (Note 1)	Internally Limited
Operating Temperature Range (T_A)	0°C to +70°C
Maximum Junction Temperature	
(K Package)	150°C
(T Package)	150°C
Storage Temperature Range	−65°C to +150°C
Lead Temperature (Soldering, 10 sec.)	
TO-3 Package K	300°C
TO-220 Package T	230°C

Electrical Characteristics LM78XXC (Note 2) 0°C ≤ Tj ≤ 125°C unless otherwise noted.

Output Voltage				5V			12V			15V			Units
Input Voltage (unless otherwise noted)				10V			19V			23V			
Symbol	Parameter	Conditions		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_O	Output Voltage	T_j = 25°C, 5 mA ≤ I_O ≤ 1A		4.8	5	5.2	11.5	12	12.5	14.4	15	15.6	V
		P_D ≤ 15W, 5 mA ≤ I_O ≤ 1A V_{MIN} ≤ V_{IN} ≤ V_{MAX}		4.75 (7.5 ≤ V_{IN} ≤ 20)		5.25	11.4 (14.5 ≤ V_{IN} ≤ 27)		12.6	14.25 (17.5 ≤ V_{IN} ≤ 30)		15.75	V V
ΔV_O	Line Regulation	I_O = 500 mA	T_j = 25°C ΔV_{IN}		3 (7 ≤ V_{IN} ≤ 25)	50		4 14.5 ≤ V_{IN} ≤ 30)	120		4 (17.5 ≤ V_{IN} ≤ 30)	150	mV V
			0°C ≤ T_j ≤ +125°C ΔV_{IN}			50 (8 ≤ V_{IN} ≤ 20)			120 (15 ≤ V_{IN} ≤ 27)			150 (18.5 ≤ V_{IN} ≤ 30)	mV V
		I_O ≤ 1A	T_j = 25°C ΔV_{IN}			50 (7.5 ≤ V_{IN} ≤ 20)			120 (14.6 ≤ V_{IN} ≤ 27)			150 (17.7 ≤ V_{IN} ≤ 30)	mV V
			0°C ≤ T_j ≤ +125°C ΔV_{IN}			25 (8 ≤ V_{IN} ≤ 12)			60 (16 ≤ V_{IN} ≤ 22)			75 (20 ≤ V_{IN} ≤ 26)	mV V
ΔV_O	Load Regulation	T_j = 25°C	5 mA ≤ I_O ≤ 1.5A 250 mA ≤ I_O ≤ 750 mA		10 25	50		12 60	120		12	150 75	mV mV
		5 mA ≤ I_O ≤ 1A, 0°C ≤ T_j ≤ +125°C				50			120			150	mV
I_Q	Quiescent Current	I_O ≤ 1A	T_j = 25°C 0°C ≤ T_j ≤ +125°C			8 8.5			8 8.5			8 8.5	mA mA
ΔI_Q	Quiescent Current Change	5 mA ≤ I_O ≤ 1A				0.5			0.5			0.5	mA
		T_j = 25°C, I_O ≤ 1A V_{MIN} ≤ V_{IN} ≤ V_{MAX}				1.0 (7.5 ≤ V_{IN} ≤ 20)			1.0 (14.6 ≤ V_{IN} ≤ 27)			1.0 (17.9 ≤ V_{IN} ≤ 30)	mA V
		I_O ≤ 500 mA, 0°C ≤ T_j ≤ +125°C V_{MIN} ≤ V_{IN} ≤ V_{MAX}				1.0 (7 ≤ V_{IN} ≤ 25)			1.0 (14.5 ≤ V_{IN} ≤ 30)			1.0 (17.5 ≤ V_{IN} ≤ 30)	mA V
V_N	Output Noise Voltage	T_A = 25°C, 10 Hz ≤ f ≤ 100 kHz			40			75			90		μV
$\frac{\Delta V_{IN}}{\Delta V_{OUT}}$	Ripple Rejection	f = 120 Hz { I_O ≤ 1A, T_j = 25°C or I_O ≤ 500 mA, 0°C ≤ T_j ≤ +125°C }		62 62	80		55 55	72		54 54	70		dB dB
		V_{MIN} ≤ V_{IN} ≤ V_{MAX}		(8 ≤ V_{IN} ≤ 18)			(15 ≤ V_{IN} ≤ 25)			(18.5 ≤ V_{IN} ≤ 28.5)			V
R_O	Dropout Voltage	T_j = 25°C, I_{OUT} = 1A			2.0			2.0			2.0		V
	Output Resistance	f = 1 kHz			8			18			19		mΩ
	Short-Circuit Current	T_j = 25°C			2.1			1.5			1.2		A
	Peak Output Current	T_j = 25°C			2.4			2.4			2.4		A
	Average TC of V_{OUT}	0°C ≤ T_j ≤ +125°C, I_O = 5 mA			0.6			1.5			1.8		mV/°C
V_{IN}	Input Voltage Required to Maintain Line Regulation	T_j = 25°C, I_O ≤ 1A			7.5			14.6			17.7		V

Note 1: Thermal resistance of the TO-3 package (K, KC) is typically 4°C/W junction to case and 35°C/W case to ambient. Thermal resistance of the TO-220 package (T) is typically 4°C/W junction to case and 50°C/W case to ambient.

Note 2: All characteristics are measured with capacitor across the input of 0.22 μF, and a capacitor across the output of 0.1 μF. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.

ANNEXURE - 5

Order this document by MC7900/D

MOTOROLA

MC7900 Series

Three-Terminal Negative Voltage Regulators

THREE–TERMINAL NEGATIVE FIXED VOLTAGE REGULATORS

The MC7900 series of fixed output negative voltage regulators are intended as complements to the popular MC7800 series devices. These negative regulators are available in the same seven–voltage options as the MC7800 devices. In addition, one extra voltage option commonly employed in MECL systems is also available in the negative MC7900 series.

Available in fixed output voltage options from –5.0 V to –24 V, these regulators employ current limiting, thermal shutdown, and safe–area compensation – making them remarkably rugged under most operating conditions. With adequate heatsinking they can deliver output currents in excess of 1.0 A.

- No External Components Required
- Internal Thermal Overload Protection
- Internal Short Circuit Current Limiting
- Output Transistor Safe–Area Compensation
- Available in 2% Voltage Tolerance (See Ordering Information)

T SUFFIX
PLASTIC PACKAGE
CASE 221A

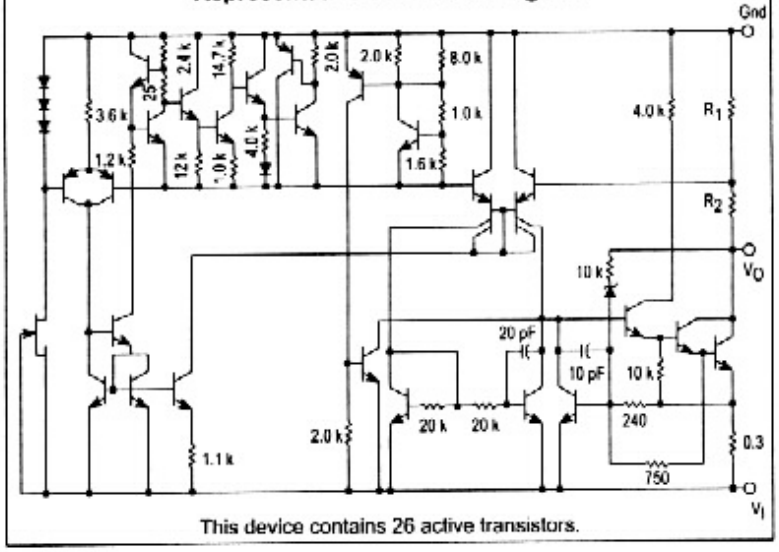
Heatsink surface connected to Pin 2.

Pin 1. Ground
2. Input
3. Output

D2T SUFFIX
PLASTIC PACKAGE
CASE 936
(D^2PAK)

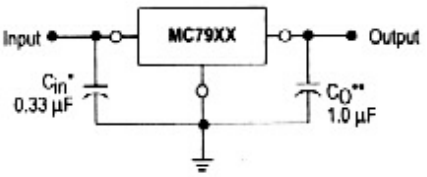
Heatsink surface (shown as terminal 4 in case outline drawing) is connected to Pin 2.

Representative Schematic Diagram



This device contains 26 active transistors.

STANDARD APPLICATION



A common ground is required between the input and the output voltages. The input voltage must remain typically 2.0 V above more negative even during the high point of the input ripple voltage.

XX, These two digits of the type number indicate nominal voltage.
* C_{in} is required if regulator is located an appreciable distance from power supply filter.
** C_O improve stability and transient response.

ORDERING INFORMATION

Device	Output Voltage Tolerance	Operating Temperature Range	Package
MC79XXACD2T	2%	T_J = 0° to +125°C	Surface Mount
MC79XXCD2T	4%		
MC79XXACT	2%		Insertion Mount
MC79XXCT	4%		
MC79XXBD2T	4%	T_J = –40° to +125°C	Surface Mount
MC79XXBT			Insertion Mount

XX indicates nominal voltage.

DEVICE TYPE/NOMINAL OUTPUT VOLTAGE

MC7905	5.0 V	MC7912	12 V
MC7905.2	5.2 V	MC7915	15 V
MC7906	6.0 V	MC7918	28 V
MC7908	8.0 V	MC7924	24 V

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MAXIMUM RATINGS (T_A = +25°C, unless otherwise noted.)

Rating	Symbol	Value	Unit
Input Voltage (−5.0 V ≥ V_O ≥ −18 V) (24 V)	V_I	−35 −40	Vdc
Power Dissipation Case 221A T_A = +25°C Thermal Resistance, Junction–to–Ambient Thermal Resistance, Junction–to–Case Case 936 (D^2PAK) T_A = +25°C Thermal Resistance, Junction–to–Ambient Thermal Resistance, Junction–to–Case	 P_D θ_{JA} θ_{JC} P_D θ_{JA} θ_{JC}	 Internally Limited 65 5.0 Internally Limited 70 5.0	 W °C/W °C/W W °C/W °C/W
Storage Junction Temperature Range	T_{stg}	−65 to +150	°C
Junction Temperature	T_J	+150	°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	65	°C/W
Thermal Resistance, Junction–to–Case	$R_{\theta JC}$	5.0	°C/W

MC7905C
ELECTRICAL CHARACTERISTICS (V_I = −10 V, I_O = 500 mA, 0°C < T_J < +125°C, unless otherwise noted.)

Characteristics	Symbol	Min	Typ	Max	Unit
Output Voltage (T_J = +25°C)	V_O	−4.8	−5.0	−5.2	Vdc
Line Regulation (Note 1) (T_J = +25°C, I_O = 100 mA) −7.0 Vdc ≥ V_I ≥ −25 Vdc −8.0 Vdc ≥ V_I ≥ −12 Vdc (T_J = +25°C, I_O = 500 mA) −7.0 Vdc ≥ V_I ≥ −25 Vdc −8.0 Vdc ≥ V_I ≥ −12 Vdc	Reg_{line}	 – – – –	 7.0 2.0 35 8.0	 50 25 100 50	mV
Load Regulation, T_J = +25°C (Note 1) 5.0 mA ≤ I_O ≤ 1.5 A 250 mA ≤ I_O ≤ 750 mA	Reg_{load}	 – –	 11 4.0	 100 50	mV
Output Voltage −7.0 Vdc ≥ V_I ≥ −20 Vdc, 5.0 mA ≤ I_O ≤ 1.0 A, P ≤ 15 W	V_O	−4.75	–	−5.25	Vdc
Input Bias Current (T_J = +25°C)	I_{IB}	–	4.3	8.0	mA
Input Bias Current Change −7.0 Vdc ≥ V_I ≥ −25 Vdc 5.0 mA ≤ I_O ≤ 1.5 A	ΔI_{IB}	 – –	 – –	 1.3 0.5	mA
Output Noise Voltage (T_A = +25°C, 10 Hz ≤ f ≤ 100 kHz)	V_n	–	40	–	μV
Ripple Rejection (I_O = 20 mA, f = 120 Hz)	RR	–	70	–	dB
Dropout Voltage I_O = 1.0 A, T_J = +25°C	V_I–V_O	–	2.0	–	Vdc
Average Temperature Coefficient of Output Voltage I_O = 5.0 mA, 0°C ≤ T_J ≤ +125°C	$\Delta V_O/\Delta T$	–	−1.0	–	mV/°C

NOTE: 1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

MC7905AC
ELECTRICAL CHARACTERISTICS (V_I = −10 V, I_O = 500 mA, 0°C < T_J < +125°C, unless otherwise noted.)

Characteristics	Symbol	Min	Typ	Max	Unit
Output Voltage (T_J = +25°C)	V_O	−4.9	−5.0	−5.1	Vdc
Line Regulation (Note 1) −8.0 Vdc ≥ V_I ≥ −12 Vdc; I_O = 1.0 A, T_J = +25°C −8.0 Vdc ≥ V_I ≥ −12 Vdc; I_O = 1.0 A −7.5 Vdc ≥ V_I ≥ −25 Vdc; I_O = 500 mA −7.0 Vdc ≥ V_I ≥ −20 Vdc; I_O = 1.0 A, T_J = +25°C	Reg_{line}	 – – – –	 2.0 7.0 7.0 6.0	 25 50 50 50	mV
Load Regulation (Note 1) 5.0 mA ≤ I_O ≤ 1.5 A, T_J = +25°C 250 mA ≤ I_O ≤ 750 mA 5.0 mA ≤ I_O ≤ 1.0 A	Reg_{load}	 – – –	 11 4.0 9.0	 100 50 100	mV
Output Voltage −7.5 Vdc ≥ V_I > −20 Vdc, 5.0 mA ≤ I_O ≤ 1.0 A, P ≤ 15 W	V_O	−4.80	–	−5.20	Vdc
Input Bias Current	I_{IB}	–	4.4	8.0	mA
Input Bias Current Change −7.5 Vdc ≥ V_I ≥ −25 Vdc 5.0 mA ≤ I_O ≤ 1.0 A 5.0 mA ≤ I_O ≤ 1.5 A, T_J = +25°C	ΔI_{IB}	 – – –	 – – –	 1.3 0.5 0.5	mA
Output Noise Voltage (T_A = +25°C, 10 Hz ≤ f ≤ 100 kHz)	V_n	–	40	–	μV
Ripple Rejection (I_O = mA, f = 120 Hz)	RR	–	70	–	dB
Dropout Voltage I_O = 1.0 A, T_J = +25°C	V_I–V_O	–	2.0	–	Vdc
Average Temperature Coefficient of Output Voltage I_O = 5.0 A, 0°C ≤ T_J ≤ +125°C	$\Delta V_O/\Delta T$	–	−1.0	–	mV/°C

MC7905.2C
ELECTRICAL CHARACTERISTICS (V_I = −10 V, I_O = 500 mA, 0°C < T_J < +125°C, unless otherwise noted.)

Characteristics	Symbol	Min	Typ	Max	Unit
Output Voltage (T_J = +25°C)	V_O	−5.0	−5.2	−5.4	Vdc
Line Regulation (Note 1) (T_J = +25°C, I_O = 100 mA) −7.2 Vdc ≥ V_I ≥ −25 Vdc −8.0 Vdc ≥ V_I ≥ −12 Vdc (T_J = +25°C, I_O = 500 mA) −7.2 Vdc ≥ V_I ≥ −25 Vdc −8.0 Vdc ≥ V_I ≥ −12 Vdc	Reg_{line}	 – – – –	 8.0 2.2 37 8.5	 52 27 105 52	mV
Load Regulation, T_J = +25°C (Note 1) 5.0 mA ≤ I_O ≤ 1.5 A 250 mA ≤ I_O ≤ 750 mA	Reg_{load}	 – –	 12 4.5	 105 52	mV
Output Voltage −7.2 Vdc ≥ V_I ≥ −20 Vdc, 5.0 mA ≤ I_O ≤ 1.0 A, P ≤ 15 W	V_O	−4.95	–	−5.45	Vdc
Input Bias Current (T_J = +25°C)	I_{IB}	–	4.3	8.0	mA
Input Bias Current Change −7.2 Vdc ≥ V_I ≥ −25 Vdc 5.0 mA ≤ I_O ≤ 1.5 A	ΔI_{IB}	 – –	 – –	 1.3 0.5	mA
Output Noise Voltage (T_A = +25°C, 10 Hz ≤ f ≤ 100 kHz)	V_n	–	42	–	μV
Ripple Rejection (I_O = 20 mA, f = 120 Hz)	RR	–	68	–	dB
Dropout Voltage I_O = 1.0 A, T_J = +25°C	V_I–V_O	–	2.0	–	Vdc
Average Temperature Coefficient of Output Voltage I_O = 5.0 mA, 0°C ≤ T_J ≤ +125°C	$\Delta V_O/\Delta T$	–	−1.0	–	mV/°C

NOTE: 1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

ANNEXURE - 6

National Semiconductor

MM54HC245A/MM74HC245A Octal TRI-STATE® Transceiver

General Description

This TRI-STATE bidirectional buffer utilizes advanced silicon-gate CMOS technology, and is intended for two-way asynchronous communication between data buses. It has high drive current outputs which enable high speed operation even when driving large bus capacitances. This circuit possesses the low power consumption and high noise immunity usually associated with CMOS circuitry, yet has speeds comparable to low power Schottky TTL circuits.

This device has an active low enable input $\overline{G}$ and a direction control input, DIR. When DIR is high, data flows from the A inputs to the B outputs. When DIR is low, data flows from the B inputs to the A outputs. The MM54HC245A/MM74HC245A transfers true data from one bus to the other.

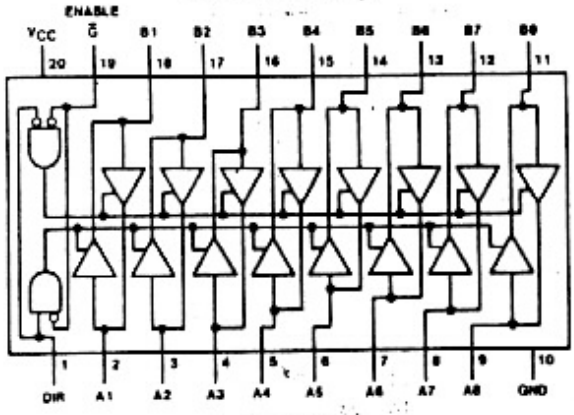
This device can drive up to 15 LS-TTL Loads, and does not have Schmitt trigger inputs. All inputs are protected from damage due to static discharge by diodes to V_{CC} and ground.

Features

- Typical propagation delay: 13 ns
- Wide power supply range: 2–6V
- Low quiescent current: 80 μA maximum (74 HC)
- TRI-STATE outputs for connection to bus oriented systems
- High output drive: 6 mA (minimum)
- Same as the '645

Connection Diagram

Dual-In-Line Package



TL/F/5185–1

Top View

Order Number MM54HC245A* or MM74HC245A*

*Please look into Section 8, Appendix D for availability of various package types.

Truth Table

Control Inputs		Operation
$\overline{G}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

H = high level, L = low level, X = irrelevant

Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage DIR and $\overline{G}$ pins (V_{IN})	−1.5 to V_{CC} +1.5V
DC Input/Output Voltage (V_{IN}, V_{OUT})	−0.5 to V_{CC} +0.5V
Clamp Diode Current (I_{CD})	±20 mA
DC Output Current, per pin (I_{OUT})	±35 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±70 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temp. (T_L) (Soldering 10 seconds)	260°C

Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temp. Range (T_A)			
MM74HC	−40	+85	°C
MM54HC	−55	+125	°C
Input Rise/Fall Times (t_r, t_f) V_{CC} = 2.0V		1000	ns
V_{CC} = 4.5V		500	ns
V_{CC} = 6.0V		400	ns

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V_{CC}	T_A = 25°C	74HC T_A = −40 to 85°C	54HC T_A = −55 to 125°C	Units
				Typ	Guaranteed Limits		
V_{IH}	Minimum High Level Input Voltage		2.0V		1.5	1.5	V
			4.5V		3.15	3.15	V
			6.0V		4.2	4.2	V
V_{IL}	Maximum Low Level Input Voltage**		2.0V		0.5	0.5	V
			4.5V		1.35	1.35	V
			6.0V		1.8	1.8	V
V_{OH}	Minimum High Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $\lvert I_{OUT}\rvert \le 20\ \mu A$	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		V_{IN} = V_{IH} or V_{IL} $\lvert I_{OUT}\rvert \le 6.0$ mA	4.5V	4.2	3.98	3.84	3.7	V
		$\lvert I_{OUT}\rvert \le 7.8$ mA	6.0V	5.7	5.48	5.34	5.2	V
V_{OL}	Maximum Low Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $\lvert I_{OUT}\rvert \le 20\ \mu A$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		V_{IN} = V_{IH} or V_{IL} $\lvert I_{OUT}\rvert \le 6.0$ mA	4.5V	0.2	0.26	0.33	0.4	V
		$\lvert I_{OUT}\rvert \le 7.8$ mA	6.0V	0.2	0.26	0.33	0.4	V
I_{IN}	Input Leakage Current ($\overline{G}$ and DIR)	V_{IN} = V_{CC} to GND	6.0V		±0.1	±1.0	±1.0	μA
I_{OZ}	Maximum TRI-STATE Output Leakage Current	V_{OUT} = V_{CC} or GND Enable $\overline{G}$ = V_{IH}	6.0V		±0.5	±5.0	±10	μA
I_{CC}	Maximum Quiescent Supply Current	V_{IN} = V_{CC} or GND I_{OUT} = 0 μA	6.0V		8.0	80	160	μA

Note 1: Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C; ceramic "J" package: −12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V ±10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

** V_{IL} limits are currently tested at 20% of V_{CC}. The above V_{IL} specification (30%) of V_{CC}) will be implemented no later than Q1, CY'89. Q = V_{IL}.

AC Electrical Characteristics $V_{CC} = 5V$, $T_A = 25°C$, $t_r = t_f = 6$ ns

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{PHL}, t_{PLH}	Maximum Propagation Delay	$C_L = 45$ pF	12	17	ns
t_{PZH}, t_{PZL}	Maximum Output Enable Time	$R_L = 1$ kΩ $C_L = 45$ pF	24	35	ns
t_{PHZ}, t_{PLZ}	Maximum Output Disable Time	$R_L = 1$ kΩ $C_L = 5$ pF	18	25	ns

AC Electrical Characteristics $V_{CC} = 2.0V$ to $6.0V$, $C_L = 50$ pF, $t_r = t_f = 6$ ns (unless otherwise specified)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25°C$	74HC $T_A = -40$ to $85°C$	54HC $T_A = -55$ to $125°C$	Units
				Typ	Guaranteed Limits		
t_{PHL}, t_{PLH}	Maximum Propagation Delay	$C_L = 50$ pF	2.0V	31	90	113	135	ns
		$C_L = 150$ pF	2.0V	41	96	116	128	ns
		$C_L = 50$ pF	4.5V	13	18	23	27	ns
		$C_L = 150$ pF	4.5V	17	22	28	33	ns
		$C_L = 50$ pF	6.0V	11	15	19	23	ns
		$C_L = 150$ pF	6.0V	14	19	23	28	ns
t_{PZH}, t_{PZL}	Maximum Output Enable Time	$R_L = 1$ kΩ						
		$C_L = 50$ pF	2.0V	71	190	240	285	ns
		$C_L = 150$ pF	2.0V	81	240	300	360	ns
		$C_L = 50$ pF	4.5V	26	38	48	57	ns
		$C_L = 150$ pF	4.5V	31	48	60	72	ns
		$C_L = 50$ pF	6.0V	21	32	41	48	ns
		$C_L = 150$ pF	6.0V	25	41	51	61	ns
t_{PHZ}, t_{PLZ}	Maximum Output Disable Time	$R_L = 1$ kΩ	2.0V	39	135	169	203	ns
		$C_L = 50$ pF	4.5V	20	27	34	41	ns
			6.0V	18	23	29	34	ns
t_{TLH}, t_{THL}	Output Rise and Fall Time	$C_L = 50$ pF	2.0V	20	60	75	90	ns
			4.5V	6	12	15	18	ns
			6.0V	5	10	13	15	ns
C_{PD}	Power Dissipation Capacitance (Note 5)	$\overline{G} = V_{IL}$		50				pF
		$G = V_{IH}$		5				pF
C_{IN}	Maximum Input Capacitance			5	10	10	10	pF
$C_{IN/OUT}$	Maximum Input/Output Capacitance, A or B			15	20	20	20	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.